

I2701F

ELECTRICALLY INSULATIVE FILM

TECHNICAL DATA

Product Description

TechFilm I2701F is a high performance electrically isolating B-staged film adhesive specially formulated for bonding at lower temperatures. TechFilm I2701F will cure at temperatures above 90°C. It features good chemical, heat, and moisture resistance.

APPLICATIONS

- General purpose adhesive
- Electronics board laminate

FEATURES

- Electrically insulative
- B-staged film
- Chemical, heat, moisture resistant

RECOMMENDED SUBSTRATES

- Copper
- Aluminium

CURED PROPERTIES

Property	Value	Test Method
Color	Transparent/Translucent	Visual
Specific Gravity	1.2	QPTEST002
Glass Transition Temperature, °C	110	N/A
Volume Resistivity @ 25°C, Ohm-cm	1×10^{12}	N/A
Weight Loss at 150°C, TGA, 20°C/min, N ₂ , %	0.35	N/A
at 200°C	0.95	N/A

TENSILE SHEAR STRENGTH

Property	Value	Test Method
to Aluminum @ 25°C, psi	2350	N/A
to 101 Copper @ 25°C, psi	3050	N/A

CURE OVERVIEW

Property	Value	Test Method
Cure Time @ 150°C, min	30	N/A
Cure Time @ 130°C, min	60	N/A
Cure Time @ 100°C, min	180	N/A

Storage: Store in dry conditions, out of sunlight and in tightly sealed containers.

Shelf Life: 24 hours @ 20°C Two weeks @ 10°C Two months @ -10°C One year @ -40°C

Revision Number: 2 Date: 20 December, 2016

Resin Designs, LLC 11 State Street Woburn, MA 01801 www.resindesigns.com P 781-935-3133 F 781-935-3144

RESIN DESIGNS, LLC MAKES NO EXPRESS OR IMPLIED REPRESENTATIONS OR WARRANTIES, INCLUDING WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR OTHERWISE, WITH RESPECT TO THIS PRODUCT AND GUARANTEES NO PARTICULAR OUTCOME OR RESULT FROM ITS USE. RESIN DESIGNS' LIABILITY TO CUSTOMER WITH RESPECT TO THIS PRODUCT SHALL IN NO EVENT EXCEED THE AMOUNT PAID BY CUSTOMER FOR IT.